

AMENDMENTS TO THE DRAWINGS

New Fig. 11 is added for consideration. Support for new Fig. 11 can be found at Page 11 of the Specification at Paragraph [0046] and at Claims 5 and 6 of the originally filed application.

Attachment: New Fig. 11.

REMARKS

Applicant's representative would like to thank Examiner Pham for the courtesies extending during a telephonic interview on March 9, 2006. During the interview, the Examiner suggested amending independent Claim 1 such that independent Claim 1 sequentially calls for forming a first conductive layer, applying a layer of resin, and forming second conductive layer. Independent Claim 1 has been amended in accordance with the Examiner's suggestion and is therefore believed to be in condition for allowance.

Claims 1-4 are now pending in the application. By this paper, Claims 1, 3, and 4 have been amended and Claims 5 and 6 and have been cancelled without prejudice or disclaimer of the subject matter contained therein. The basis for these amendments can be found throughout the specification, claims, and drawings originally filed. No new matter has been added. The preceding amendments and the following remarks are believed to be fully responsive to the outstanding Office Action and are believed to place the application in condition for allowance.

The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

DRAWINGS

Fig. 11 is added for consideration. Support for new Fig. 11 can be found at Page 11 of the Specification at Paragraph [0046] and in originally filed Claims 5 and 6. No new matter has been added.

SPECIFICATION

Paragraph [0028.1] has been added following Paragraph [0028] to describe new Fig. 11. In addition, Paragraph [0046] has been amended to describe the conductive layer (5) as including a first conductive layer (5a) and a second conductive layer (5b). As noted above with respect to new Fig. 11, support for Paragraph [0028.1] and amended Paragraph [0046] can be found in Paragraph [0046] and Claims 5 and 6 of the originally filed application. Accordingly, Applicant respectfully submits that new Paragraph [0028.1], as well as the amendments to Paragraph [0046], are adequately supported by the specification and claims as filed.

CLAIM OBJECTIONS

At the outset, Applicant respectfully submits that this objection is moot with respect to Claim 5 as Claim 5 has been cancelled without prejudice or disclaimer of the subject matter contained therein. Accordingly, reconsideration and withdrawal of the objection is respectfully requested.

The Examiner states that the term "the element" lacks antecedent basis at Line 8 and states that the term "a height of the layer" at Line 9 should be amended. Accordingly, Applicant has replaced the term "the element" with the term "the semiconductor element" at Line 8 and has replaced the term "a height of the layer" with the term "a height of the resin layer" at Line 9. Accordingly, Applicant respectfully submits that Claim 1 is in condition for allowance. Accordingly, reconsideration and withdrawal of the objections is respectfully requested.

REJECTION UNDER 35 U.S.C. § 102

Claims 1-4 stand rejected under 35 U.S.C. § 102(b) as being anticipated by Takashi Okano (JP 04030533).

This rejection is respectfully traversed.

Independent Claim 1 has been amended to include the allowable subject matter identified by the Examiner. Specifically, independent Claim 1 has been amended to include the allowable subject matter of Claim 6. Accordingly, Applicant respectfully submits that independent Claim 1, as well as Claims 2-4, dependent therefrom, are in condition for allowance. Therefore, reconsideration and withdrawal of the rejection is respectfully requested.

REJECTION UNDER 35 U.S.C. § 103

Claim 5 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Takashi Okano (JP 04030533) in view of Mukai et al. (JP 56164556).

This rejection is respectfully traversed.

Applicant respectfully submits that this rejection is moot as Claim 5 has been cancelled without prejudice or disclaimer the subject matter contained therein. Accordingly, reconsideration and withdrawal of the rejection is respectfully requested.

ALLOWABLE SUBJECT MATTER

The Examiner states that Claim 6 would be allowable if rewritten in independent form. Accordingly, Applicant has amended independent Claim 1 to include the limitations of Claims 5 and 6. Therefore, Applicant respectfully submits that independent Claim 1, as well as Claims 2-4, dependent therefrom, are in condition for allowance.

CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action, and as such, the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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FIG. 11

